

SN74F1056

8-BIT SCHOTTKY BARRIER DIODE BUS-TERMINATION ARRAY

SDFS085 – AUGUST 1992

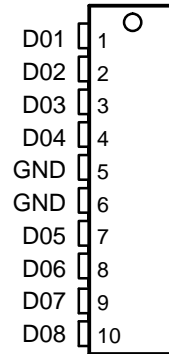
- Designed to Reduce Reflection Noise
- Repetitive Peak Forward Current . . . 300 mA
- 8-Bit Array Structure Suited for Bus-Oriented Systems

description

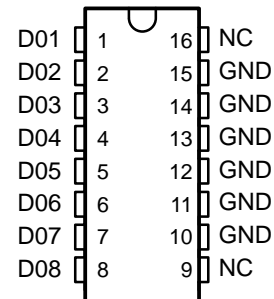
This Schottky barrier diode bus-termination array is designed to reduce reflection noise on memory bus lines. This device consists of an 8-bit high-speed Schottky diode array suitable for GND clamp.

The SN74F1056 is characterized for operation from 0°C to 70°C.

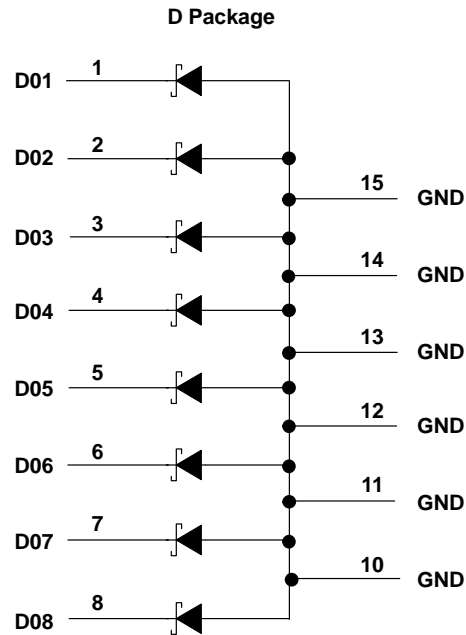
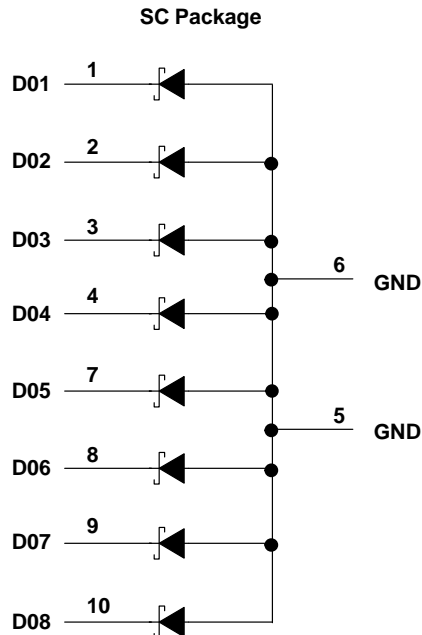
SC PACKAGE
(TOP VIEW)



D PACKAGE
(TOP VIEW)



schematic diagrams



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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SN74F1056

8-BIT SCHOTTKY BARRIER DIODE

BUS-TERMINATION ARRAY

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Steady-state reverse voltage, V_R	7 V
Continuous forward current, I_F : Any D terminal from GND	50 mA
Total through all GND terminals	170 mA
Repetitive peak forward current, I_{FRM}^{\ddagger} : Any D terminal from GND	300 mA
Total through all GND terminals	1.2 A
Continuous total power dissipation at (or below) 25°C free-air temperature	500 mW
Operating free-air temperature range	0°C to 70°C
Storage temperature range	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[‡] These values apply for $t_W \leq 100 \mu s$, duty cycle $\leq 20\%$.

electrical characteristics over recommended operating free-air temperature range (unless other noted)

single-diode operation (see Note 1)

PARAMETER	TEST CONDITIONS	MIN	TYP [§]	MAX	UNIT
I_R Static reverse current	$V_R = 7 V$			2	μA
V_F Static forward voltage	$I_F = 18 mA$		0.8	1	V
	$I_F = 50 mA$		1	1.2	
V_{FM} Peak forward voltage	$I_F = 200 mA$		1.23		V
C_t Total capacitance	$V_R = 0, f = 1 MHz$		3	3.75	pF
	$V_R = 2 V, f = 1 MHz$		2.5	3	

[§] All typical values are at $T_A = 25^\circ C$.

NOTE 1: Test conditions and limits apply separately to each of the diodes. The diodes not under test are open-circuited during the measurement of these characteristics.

multiple-diode operation

PARAMETER	TEST CONDITIONS	MIN	TYP [§]	MAX	UNIT
I_X Internal crosstalk current	Total GND current = 1.2 A, See Note 2		10	50	μA

NOTE 2: I_X is measured under the following conditions with one diode static, all others switching:

- .. Switching diodes: $t_W = 100 \mu s$, duty cycle = 20%;
- .. Static diode: $V_R = 5 V$; the static diode input current is the internal crosstalk current I_X .

switching characteristics, $T_A = 25^\circ C$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{rr} Reverse recovery time	$I_F = 10 mA, I_{RM(REC)} = 10 mA, I_{R(REC)} = 1 mA, R_L = 100 \Omega$		5	7	ns

undershoot characteristics

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{US} Undershoot voltage	$t_f = 2 ns, t_W = 50 ns, V_{IH} = 5 V, V_{IL} = 0, Z_S = 25 \Omega, Z_O = 50 \Omega, L = 36\text{-inch coax}$		0.6	0.7	V



APPLICATION INFORMATION

Large negative transients occurring at the inputs of memory devices (DRAMs, SRAMs, EPROMs, etc.) or on the CLOCK lines of many clocked devices can result in improper operation of the devices. The SN74F1056 diode termination array helps suppress negative transients caused by transmission line reflections, crosstalk, and switching noise.

Diode terminations have several advantages when compared to resistor termination schemes. Split resistor or Thevenin equivalent termination can cause a substantial increase in power consumption. The use of a single resistor to Ground to terminate a line usually results in degradation of the output high level, resulting in reduced noise immunity. Series damping resistors placed on the outputs of the driver will reduce negative transients, but they can also increase propagation delays down the line, as a series resistor reduces the output drive capability of the driving device. Diode terminations have none of these drawbacks.

The operation of the diode arrays in reducing negative transients is explained in the following figures. The diode conducts current whenever the voltage reaches a negative value large enough for the diode to turn on. Suppression of negative transients is tracked by the current-voltage characteristic curve for that diode. A typical current voltage for the SN74F1056 is shown in Figure 1.

To illustrate how the diode arrays act to reduce negative transients at the end of a transmission line, the test setup in Figure 2(a) was evaluated. The resulting waveforms with and without the diode are shown in Figure 2(b).

The maximum effectiveness of the diode arrays in suppressing negative transients occurs when they are placed at the end of a line and/or the end of a long stub branching off a main transmission line. The diodes can also be used to reduce the negative transients that occur due to discontinuities in the middle of a line. An example of this is a slot in a backplane that is provided for an add-on card.

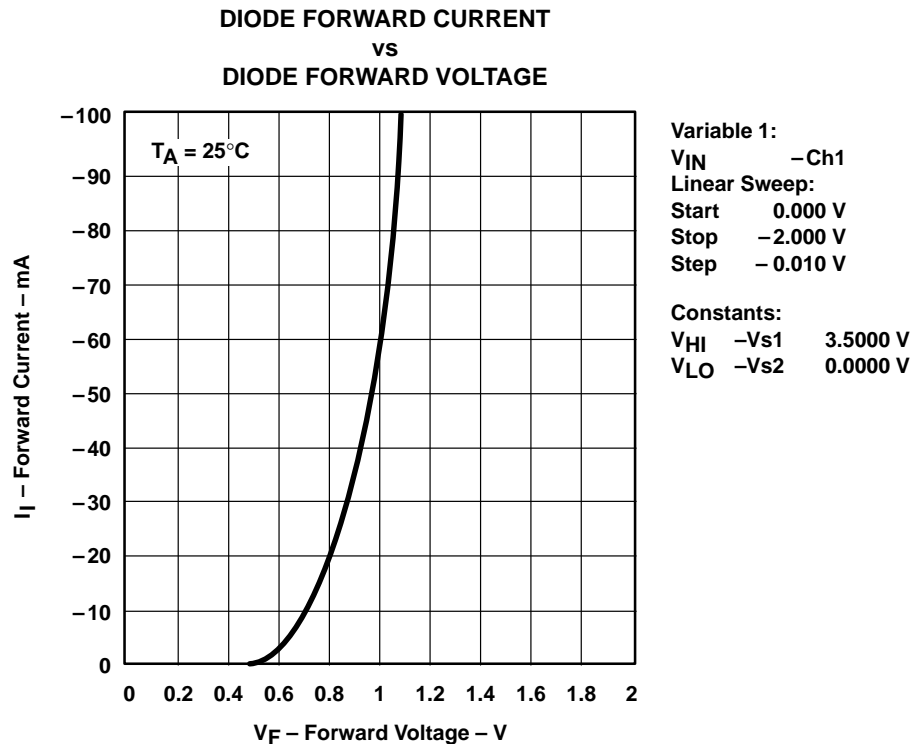
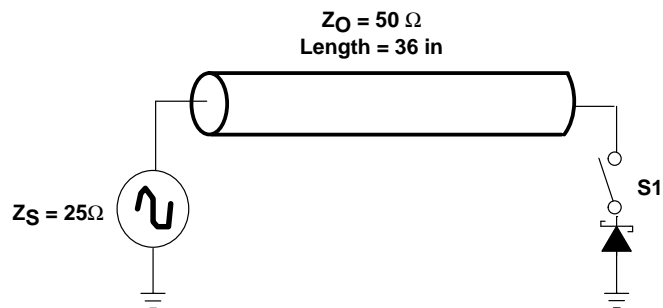
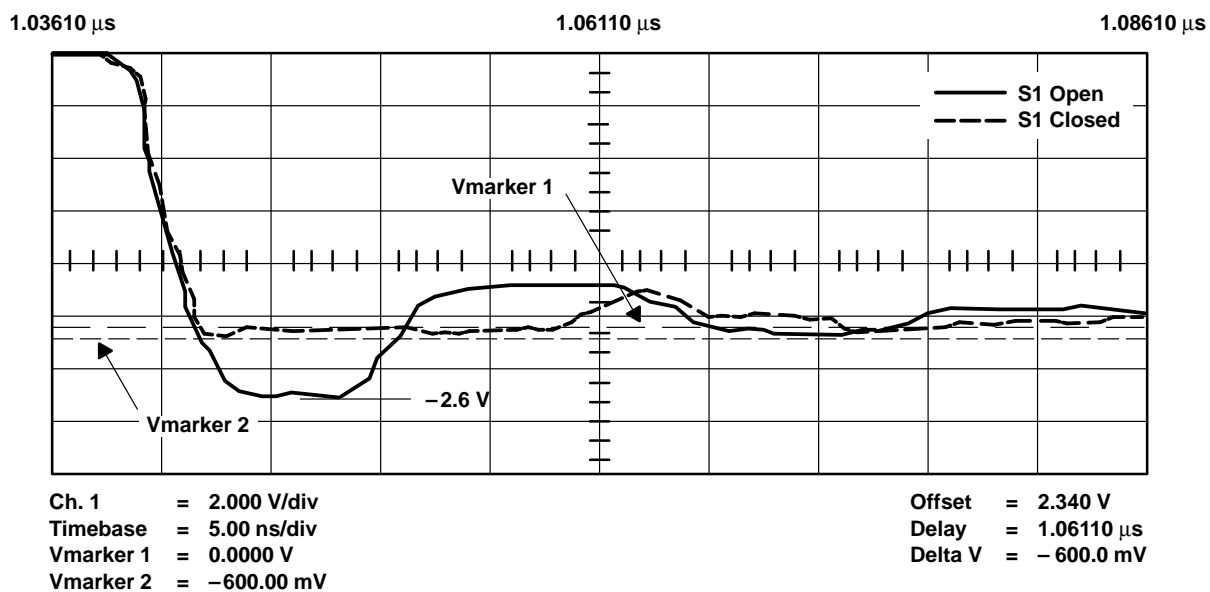


Figure 1



(a) UNDERSHOOT TEST SETUP



(b) SCOPE DISPLAY

Figure 2. Undershoot Test Setup and Scope Display

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